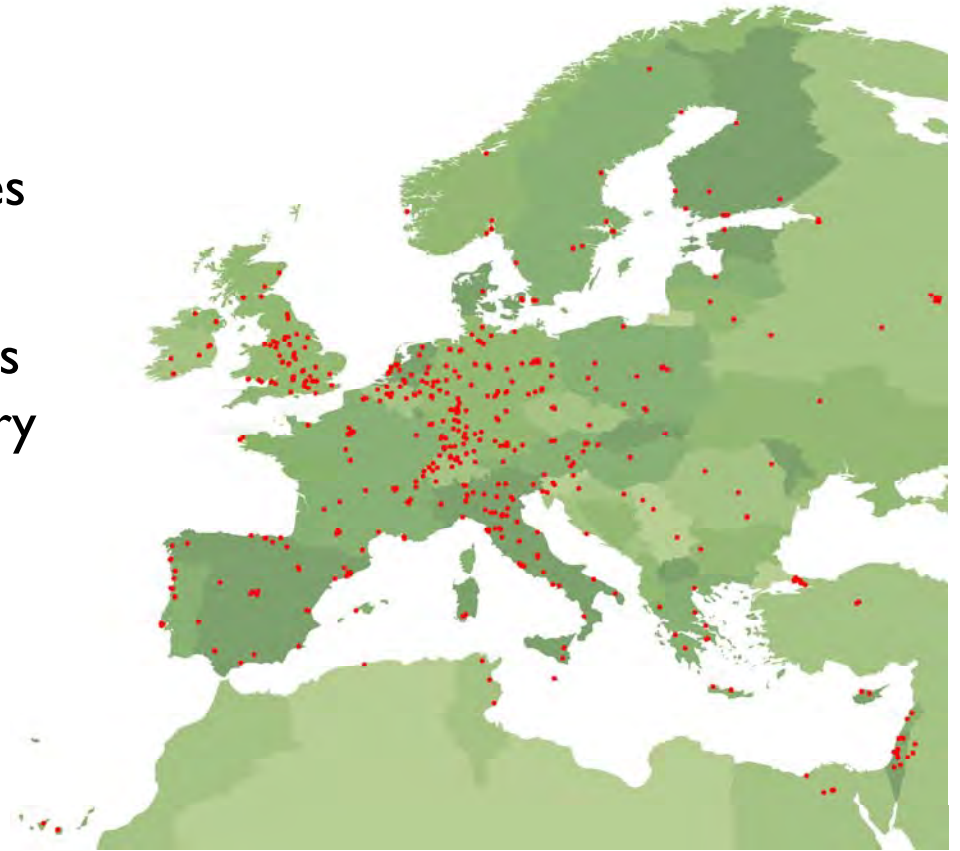


EUROPRACTICE

the Trusted One-Stop-Shop enabling Microelectronic Innovations by Academia and Start-ups

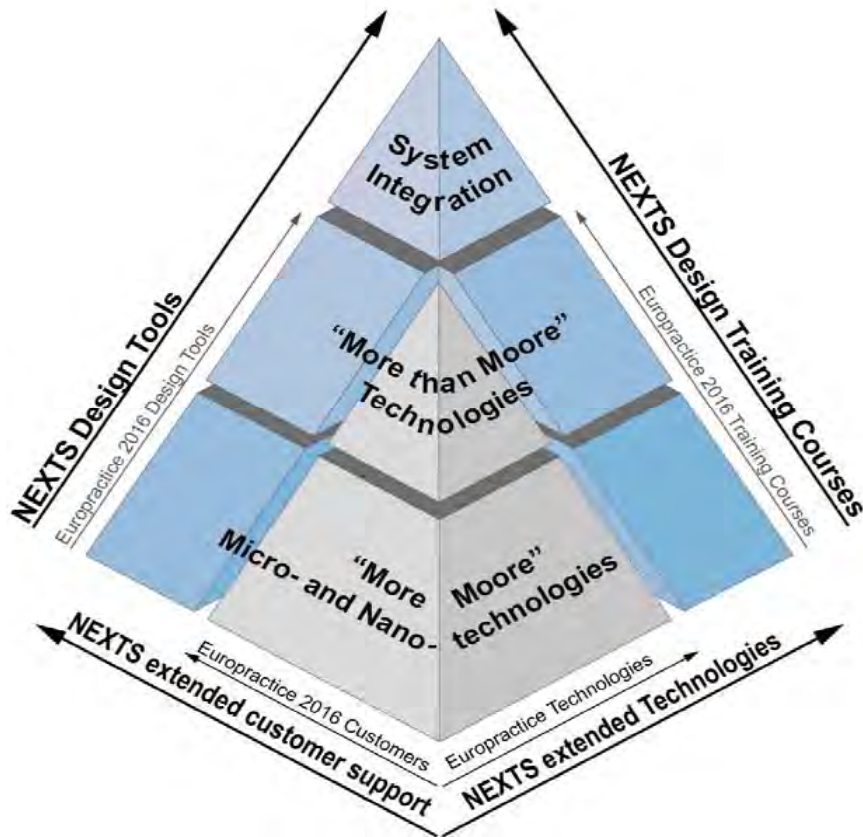
- ◆ EUROPRACTICE accelerates the use of advanced technologies, upskilling industry, and their eventual transfer to commercial foundries for industrial uptake and scale-up.
- ◆ To complement this, EUROPRACTICE enables academia to collaborate with European industry and to supply graduates with relevant skills.
 - ▶ 450 universities
 - ▶ 181 research institutes
 - ▶ In 44 countries of Europe, Middle East and Africa



- ◆ EUROPRACTICE is the result of a European training initiative launched in 1989 under the name [EUROCHIP](#), promoting microelectronics in Europe.
- ◆ Since 1995, operating under the name [EUROPRACTICE](#) (PRomoting Access to Components, Subsystems and Microsystems Technologies for Industrial Competitiveness in EUROPE).
- ◆ Since 2019, the EUROPRACTICE Service is funded through the H2020 project - [NEXTS](#)



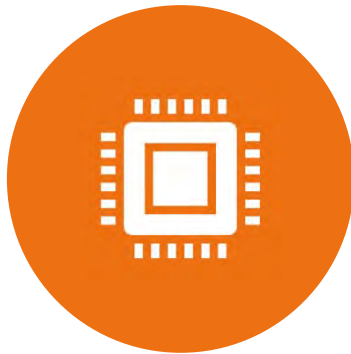
AMBITION OF THE NEXTS PROJECT



- ◆ NEXTS builds upon the well-established EUROPRACTICE service and *extends towards SMEs and System Integration*.
- ◆ The latter has been achieved thanks to new partners complementing the traditional EUROPRACTICE consortium



- ◆ EUROPRACTICE is a true one-stop shop that lowers the barrier to access all services that you need to design and fabricate electronic circuits and smart integrated systems:



FABRICATION
SERVICES



DESIGN
TOOLS



TRAINING &
WEBINARS

ASICs



ON Semiconductor®



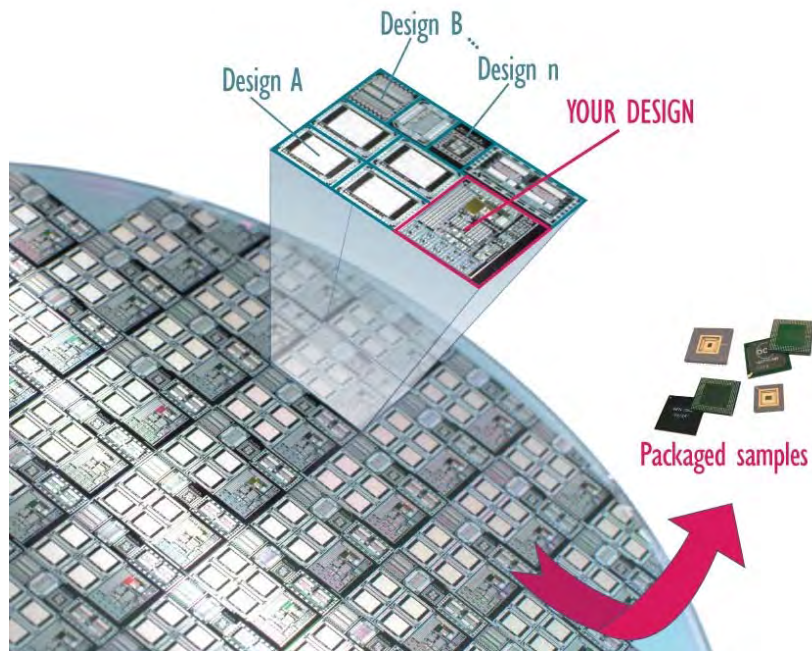
MEMS

Photonics

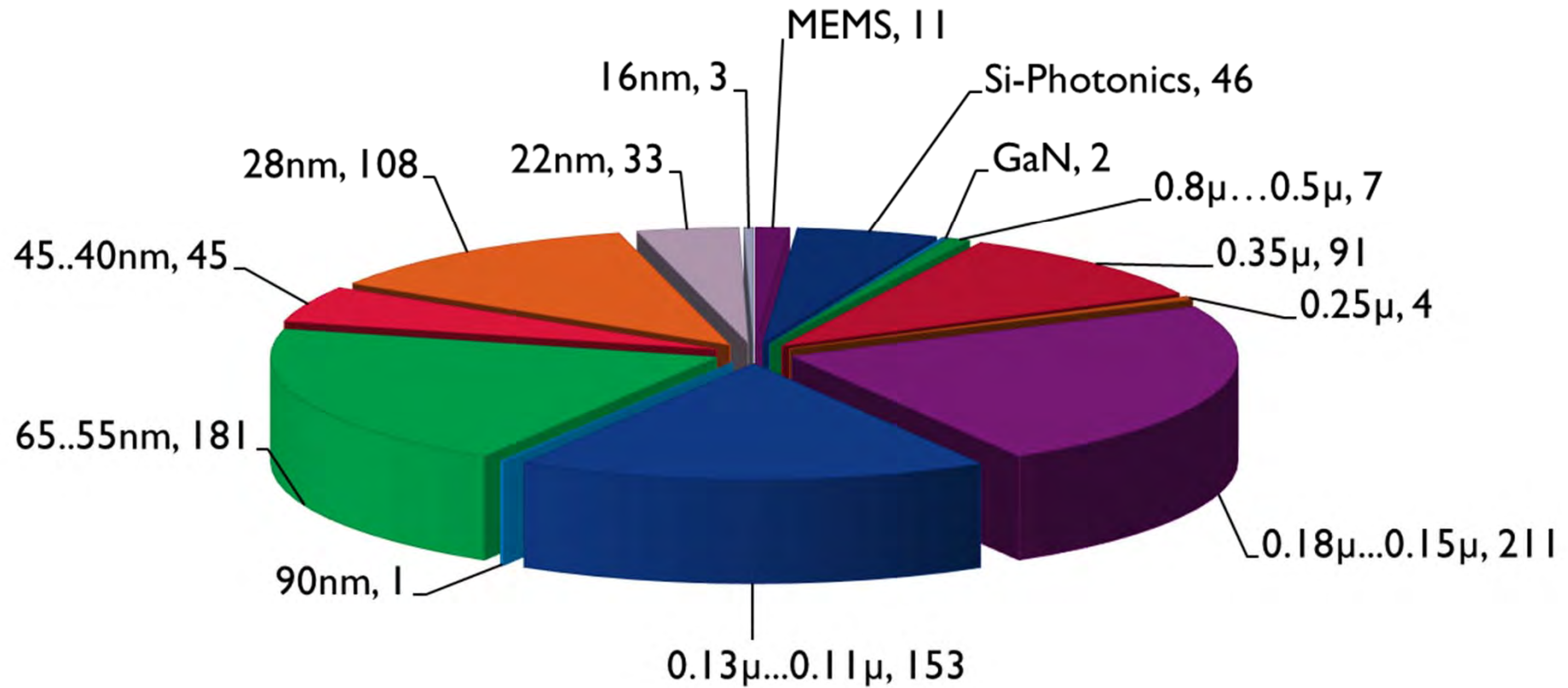
Microfluidics



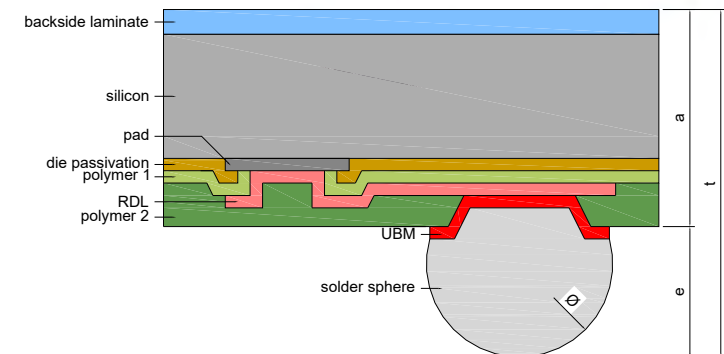
- ◆ **Multi-Project-Wafer (MPW) service:**
Combining several designs from different customers on the same mask set of a prototype run allows to share fabrication costs among the customers.

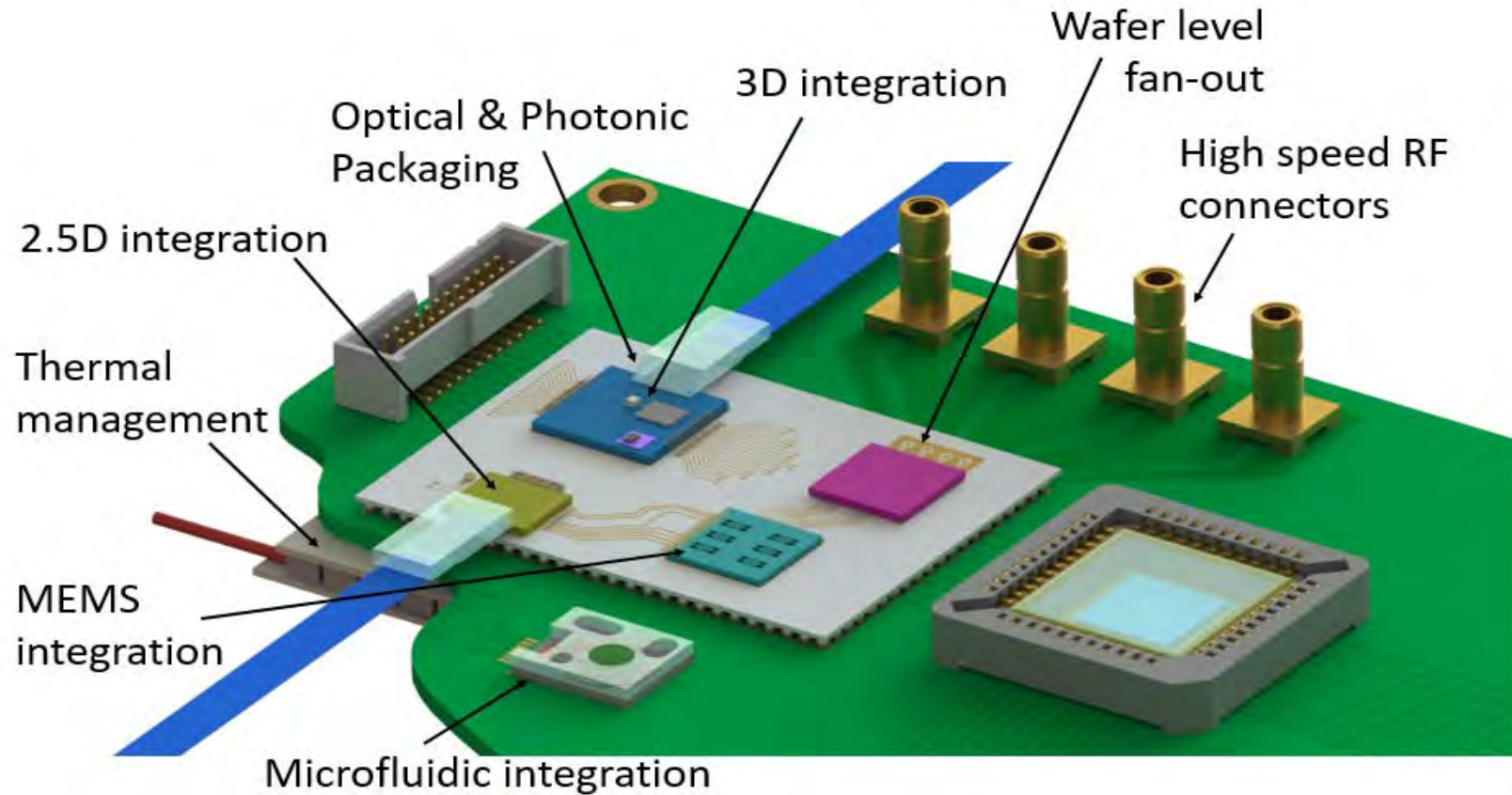


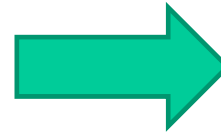
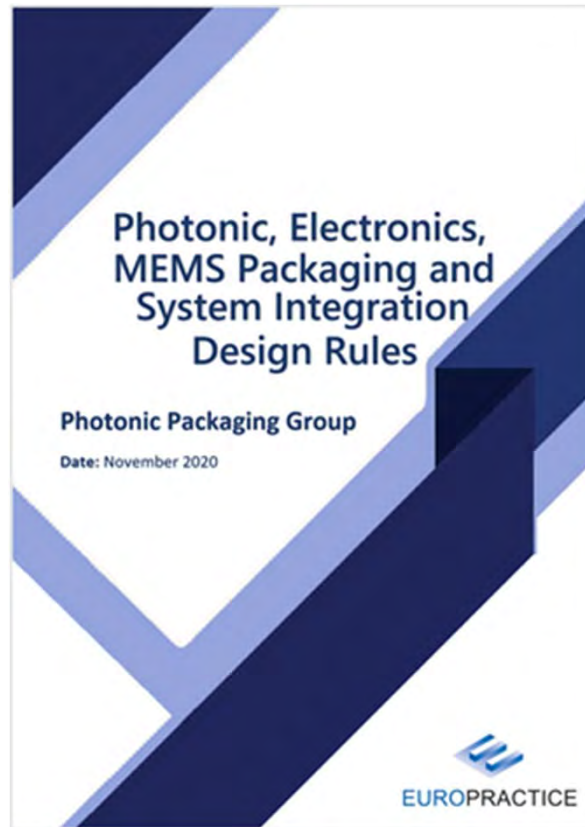
- ◆ Small- and medium-sized volume production for several technologies
- ◆ Visit the Fabrication website: www.europactice-ic.com



- ◆ Standard packages are available and used frequently
- ◆ Complex circuits and technologies require more advanced assembly techniques.
- ◆ For the very advanced and RF technologies most customers request special packaging solutions for example:
 - ▶ Wafer Level Chip Scale Package (WLCSP)
 - ▶ Flip Chip Bumping







- ◆ Platforms & Toolboxes
- ◆ Design Rules & PDK:
 - ▶ Die size and geometry
 - ▶ Die on die/substrate placement
 - ▶ Placement of Grating Couplers
 - ▶ Availability of Fibre-Arrays
 - ▶ Designing Optical Shunt
 - ▶ Placement of DC Bond-Pads
 - ▶ Arrangement of RF Bond-Pads
 - ▶ DC and RF pad sizes
 - ▶ Exclusion Zones for Epoxy
 - ▶ Best-Practice Suggestions



◆ Non-commercial licenses for academia and European start-ups; Visit www.europactice.stfc.ac.uk



- ◆ To maximize the use of design tools and technologies
- ◆ Very popular design flow courses...multiple tools, multiple vendors
 - ▶ Real design examples,
 - ▶ practical 'hands-on' exercises
- ◆ Multiple levels
 - ▶ Getting started to advanced level courses
- ◆ Multiple topics
 - ▶ Analogue IC, Digital IC, mixed-signal, low power, verification, photonics, TCAD, multiple IC technologies ...

Visit www.euopractice.stfc.ac.uk



Program includes six webinars on Microfluidics

imec

microLIQUID

IMT

micronit
microtechnologies

microfluidic
ChipShop

FAB

- ▶ **6 May at 11:00 CEST**
Introduction to Microfluidics and webinar goals
Dr. Romano Hoofman, imec
- ▶ **20 May at 11:00 CEST**
Bioassay transfer to microfluidic scale: Opportunities and Challenges
Dr. Luis Fernandez,
- ▶ **3 June at 11:00 C**
Glass fabrication measurements p
Dr. Alexios Tzannis,
- ▶ **10 June at 11:00**
Microfluidic tech lab workflow aut
Dr. Mark Olde Riek
- ▶ **17 June at 11:00**
Polymer based m
Dr. Holger Becker, i
- ▶ **8 July at 11:00 CEST**
Making silicon-ba
Integrated Micro
Oliver Foellmer, Prc

Program includes six webinars on Silicon Photonics

LionIX
INTERNATIONAL

amf
ADVANCED MICRO
FOUNDER

ip

imec

leti
SILICON

CORNERSTONE

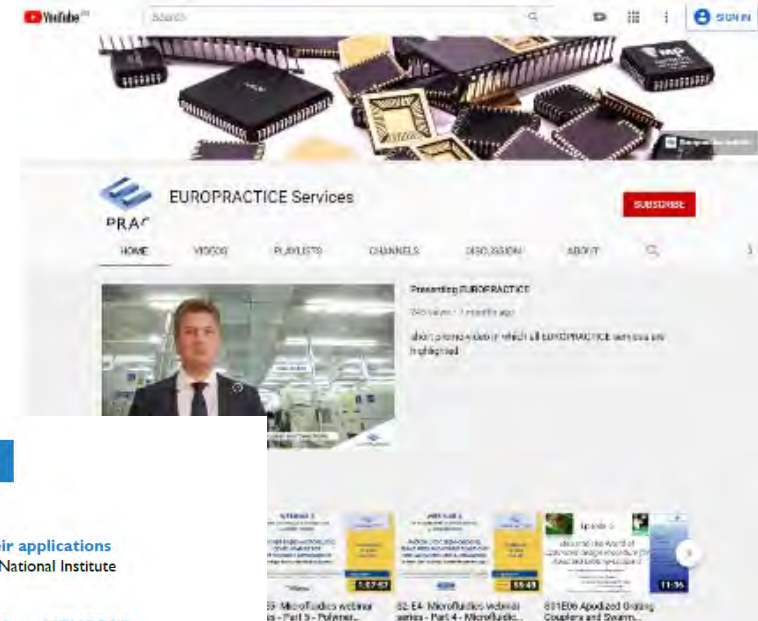
- ▶ **8 September at 14:00 CEST**
Silicon Nitride Multi-Project Wafers and why a PIC is more than a chip
Robert Grootjans, LionIX International
Preceded by a brief introduction by Dr. Ramsey Selim, EUROPRACTICE
- ▶ **15 September at 14:00 CEST**
AMF Silicon Photonic Platforms:
From Research Technology to Commercialization
Dr. Xianshu Luo, AMF
- ▶ **22 September at**
SIGe BICMOS optics system:
Dr. René Scholz,
- ▶ **6 October at 14**
Frontiers of PI
Life, Sensing &
Adil Masood, im
- ▶ **13 October at 1**
CEA-Leti's ver
Eleonore Hardy,
- ▶ **20 October at 1**
CORNERSTO
Prof Graham Re

Program includes four webinars on MEMS

Tyndall
National Institute

imec

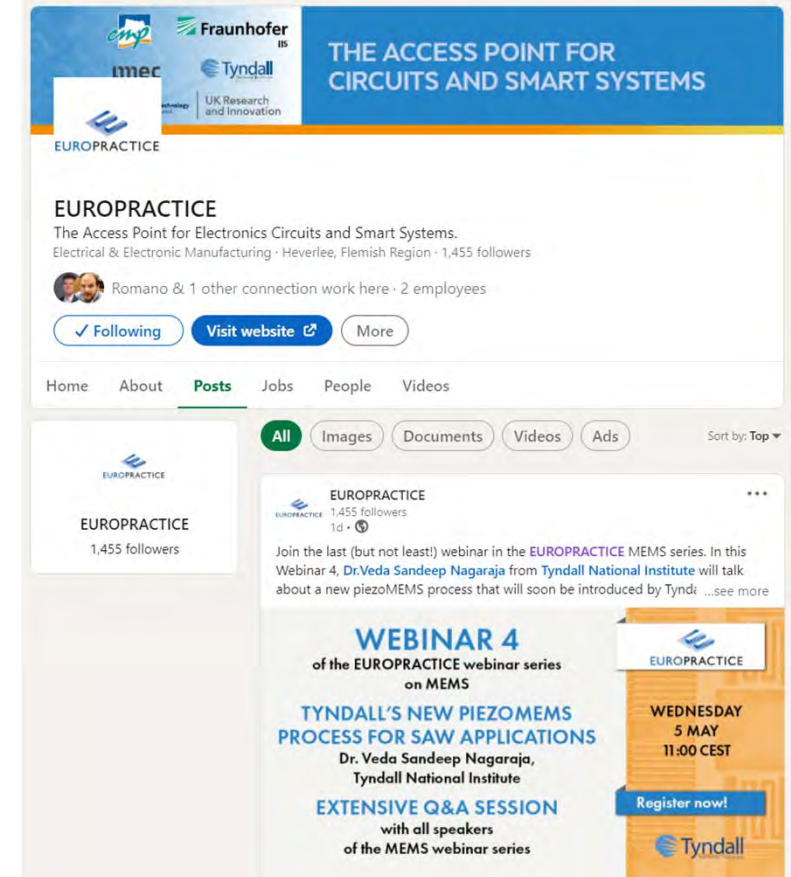
- ▶ **24 March at 11:00 CET**
Introduction to MEMS and their applications
Dr. Veda Sandeep Nagaraja, Tyndall National Institute
- ▶ **7 April at 11:00 CET**
MUMPs technology platforms from MEMSCAP
enabling low-cost prototyping
Dr. Sambuddha Khan, Tyndall National Institute
- ▶ **21 April at 11:00 CET**
XMB10: the Open Platform MEMS technology from X-FAB
for 3-Axis Inertial Sensor applications
Dr. Romano Hoofman, imec
- ▶ **5 May at 11:00 CET**
Tyndall's new PiezoMEMS process for SAW applications
Dr. Veda Sandeep Nagaraja, Tyndall National Institute



YouTube

- ◆ For latest news and updates, follow us on LinkedIn:

www.linkedin.com/company/europpractice/



The screenshot shows the LinkedIn profile for EUROPRACTICE. At the top, there are logos for partners including imec, Fraunhofer IS, and Tyndall. The profile name is EUROPRACTICE, with the tagline 'The Access Point for Electronics Circuits and Smart Systems.' It lists 'Electrical & Electronic Manufacturing · Heverlee, Flemish Region · 1,455 followers'. Below this, it shows 'Romano & 1 other connection work here · 2 employees' and buttons for 'Following', 'Visit website', and 'More'. The 'Posts' tab is selected, showing a post from EUROPRACTICE about a webinar. The post text reads: 'Join the last (but not least!) webinar in the EUROPRACTICE MEMS series. In this Webinar 4, Dr.Veda Sandeep Nagaraja from Tyndall National Institute will talk about a new piezoMEMS process that will soon be introduced by Tyndall ...see more'. The webinar details are: 'WEBINAR 4 of the EUROPRACTICE webinar series on MEMS. TYNDALL'S NEW PIEZOMEMS PROCESS FOR SAW APPLICATIONS. Dr. Veda Sandeep Nagaraja, Tyndall National Institute. EXTENSIVE Q&A SESSION with all speakers of the MEMS webinar series'. The date and time are 'WEDNESDAY 5 MAY 11:00 CEST' with a 'Register now!' button and the Tyndall logo.

